



MX27L2000

2M-BIT [256Kx8] CMOS EPROM

FEATURES

- 256Kx 8 organization
- Wide power supply range, 2.7V DC to 3.6V DC
- +12.5V programming voltage
- Fast access time: 120/150/200/250 ns
- Totally static operation
- Completely TTL compatible
- Operating current: 20mA @ 3.6V, 5MHz

- Standby current: 20uA
- Package type:
 - 32 pin ceramic DIP, plastic DIP
 - 32 pin SOP
 - 8x20mm 32-lead TSOP(I)
 - 8x14mm 32-lead TSOP(I)
 - 8x13.4mm 32-lead TSOP(I)

GENERAL DESCRIPTION

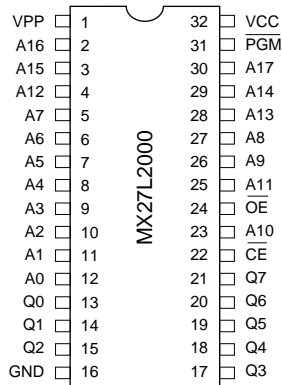
The MX27L2000 is a 3V only, 2M-bit, ultraviolet Erasable Programmable Read Only Memory. It is organized as 256K words by 8 bits per word, operates from a single +3 volt supply, has a static standby mode, and features fast single address location programming. All programming signals are TTL levels, requiring a single pulse. For programming outside from the system, existing EPROM

programmers may be used. The MX27L2000 supports an intelligent fast programming algorithm which can result in programming time of less than one minute.

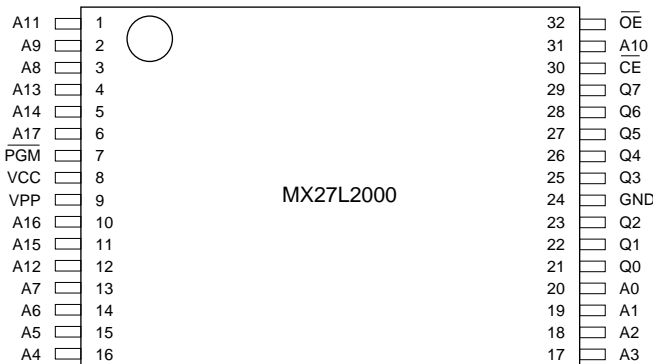
This EPROM is packaged in industry standard 32 pin dual-in-line packages, 32 lead SOP and 32 lead TSOP(I) packages.

PIN CONFIGURATIONS

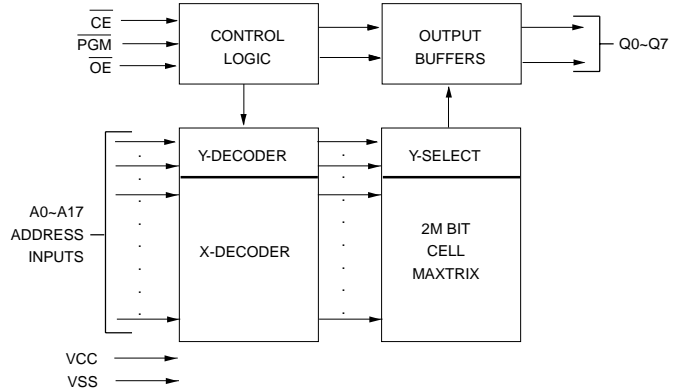
32 CDIP/PDIP/SOP



32 TSOP(I) (8x20mm, 8x14mm, 8x13.4mm)



BLOCK DIAGRAM



PIN DESCRIPTION

SYMBOL	PIN NAME
A0-A17	Address Input
Q0-Q7	Data Input/Output
CE	Chip Enable Input
OE	Output Enable Input
PGM	Programmable Enable Input
VPP	Program Supply Voltage
NC	No Internal Connection
VCC	Power Supply Pin (+5V)
GND	Ground Pin

FUNCTIONAL DESCRIPTION

THE ERASURE OF THE MX27L2000

The MX27L2000 is erased by exposing the chip to an ultraviolet light source. A dosage of 15 W seconds/cm² is required to completely erase a MX27L2000. This dosage can be obtained by exposure to an ultraviolet lamp - wavelength of 2537 Angstroms (Å) - with intensity of 12,000 uW/cm² for 15 to 20 minutes. The MX27L2000 should be directly under and about one inch from the source and all filters should be removed from the UV light source prior to erasure.

It is important to note that the MX27L2000, and similar devices, will be cleared for all bits of their programmed states with light sources having wavelengths shorter than 4000 Å. Although erasure times will be much longer than that with UV sources at 2537 Å, nevertheless the exposure to fluorescent light and sunlight will eventually erase the MX27L2000 and exposure to them should be prevented to realize maximum system reliability. If used in such an environment, the package window should be covered by an opaque label or substance.

THE PROGRAMMING OF THE MX27L2000

When the MX27L2000 is delivered, or it is erased, the chip has all 2M bits in the "ONE" or HIGH state. "ZEROS" are loaded into the MX27L2000 through the procedure of programming.

For programming, the data to be programmed is applied with 8 bits in parallel to the data pins.

Vcc must be applied simultaneously or before Vpp, and removed simultaneously or after Vpp. When programming an MXIC EPROM, a 0.1uF capacitor is required across Vpp and ground to suppress spurious voltage transients which may damage the device.

FAST PROGRAMMING

The device is set up in the fast programming mode when the programming voltage VPP = 12.75V is applied, with VCC = 6.25 V and PGM = VIH (Algorithm is shown in Figure 1). The programming is achieved by applying a single TTL low level 100us pulse to the PGM input after addresses and data line are stable. If the data is not verified, an additional pulse is applied for a maximum of 25 pulses. This process is repeated while sequencing

through each address of the device. When the programming mode is completed, the data in all address is verified at VCC = VPP = 5V ± 10%.

PROGRAM INHIBIT MODE

Programming of multiple MX27L2000s in parallel with different data is also easily accomplished by using the Program Inhibit Mode. Except for CE and OE, all like inputs of the parallel MX27L2000 may be common. A TTL low-level program pulse applied to an MX27L2000 CE input with VPP = 12.5 ± 0.5 V and PGM LOW will program that MX27L2000. A high-level CE input inhibits the other MX27L2000s from being programmed.

PROGRAM VERIFY MODE

Verification should be performed on the programmed bits to determine that they were correctly programmed. The verification should be performed with OE and CE, at VIL, PGM at VIH, and VPP at its programming voltage.

AUTO IDENTIFY MODE

The auto identify mode allows the reading out of a binary code from an EPROM that will identify its manufacturer and device type. This mode is intended for use by programming equipment for the purpose of automatically matching the device to be programmed with its corresponding programming algorithm. This mode is functional in the 25°C ± 5°C ambient temperature range that is required when programming the MX27L2000.

To activate this mode, the programming equipment must force 12.0 ± 0.5 V on address line A9 of the device. Two identifier bytes may then be sequenced from the device outputs by toggling address line A0 from VIL to VIH. All other address lines must be held at VIL during auto identify mode.

Byte 0 (A0 = VIL) represents the manufacturer code, and byte 1 (A0 = VIH), the device identifier code. For the MX27L2000, these two identifier bytes are given in the Mode Select Table. All identifiers for manufacturer and device codes will possess odd parity, with the MSB (Q7) defined as the parity bit.

READ MODE

The MX27L2000 has two control functions, both of which must be logically satisfied in order to obtain data at the outputs. Chip Enable (\overline{CE}) is the power control and should be used for device selection. Output Enable (\overline{OE}) is the output control and should be used to gate data to the output pins, independent of device selection. Assuming that addresses are stable, address access time (t_{ACC}) is equal to the delay from \overline{CE} to output (t_{CE}). Data is available at the outputs t_{QE} after the falling edge of \overline{OE} , assuming that \overline{CE} has been LOW and addresses have been stable for at least $t_{ACC} - t_{QE}$.

STANDBY MODE

The MX27L2000 has a CMOS standby mode which reduces the maximum V_{CC} current to 100 μ A. It is placed in CMOS standby when \overline{CE} is at $V_{CC} \pm 0.3$ V. The MX27L2000 also has a TTL-standby mode which reduces the maximum V_{CC} current to 1.5 mA. It is placed in TTL-standby when \overline{CE} is at V_{IH} . When in standby mode, the outputs are in a high-impedance state, independent of the \overline{OE} input.

TWO-LINE OUTPUT CONTROL FUNCTION

To accommodate multiple memory connections, a two-line control function is provided to allow for:

1. Low memory power dissipation,
2. Assurance that output bus contention will not occur.

It is recommended that \overline{CE} be decoded and used as the primary device-selecting function, while \overline{OE} be made a common connection to all devices in the array and connected to the READ line from the system control bus. This assures that all deselected memory devices are in their low-power standby mode and that the output pins are only active when data is desired from a particular memory device.

SYSTEM CONSIDERATIONS

During the switch between active and standby conditions, transient current peaks are produced on the rising and falling edges of Chip Enable. The magnitude of these transient current peaks is dependent on the output capacitance loading of the device. At a minimum, a 0.1 μ F ceramic capacitor (high frequency, low inherent inductance) should be used on each device between V_{CC} and GND to minimize transient effects. In addition, to overcome the voltage drop caused by the inductive effects of the printed circuit board traces on EPROM arrays, a 4.7 μ F bulk electrolytic capacitor should be used between V_{CC} and GND for each eight devices. The location of the capacitor should be close to where the power supply is connected to the array.

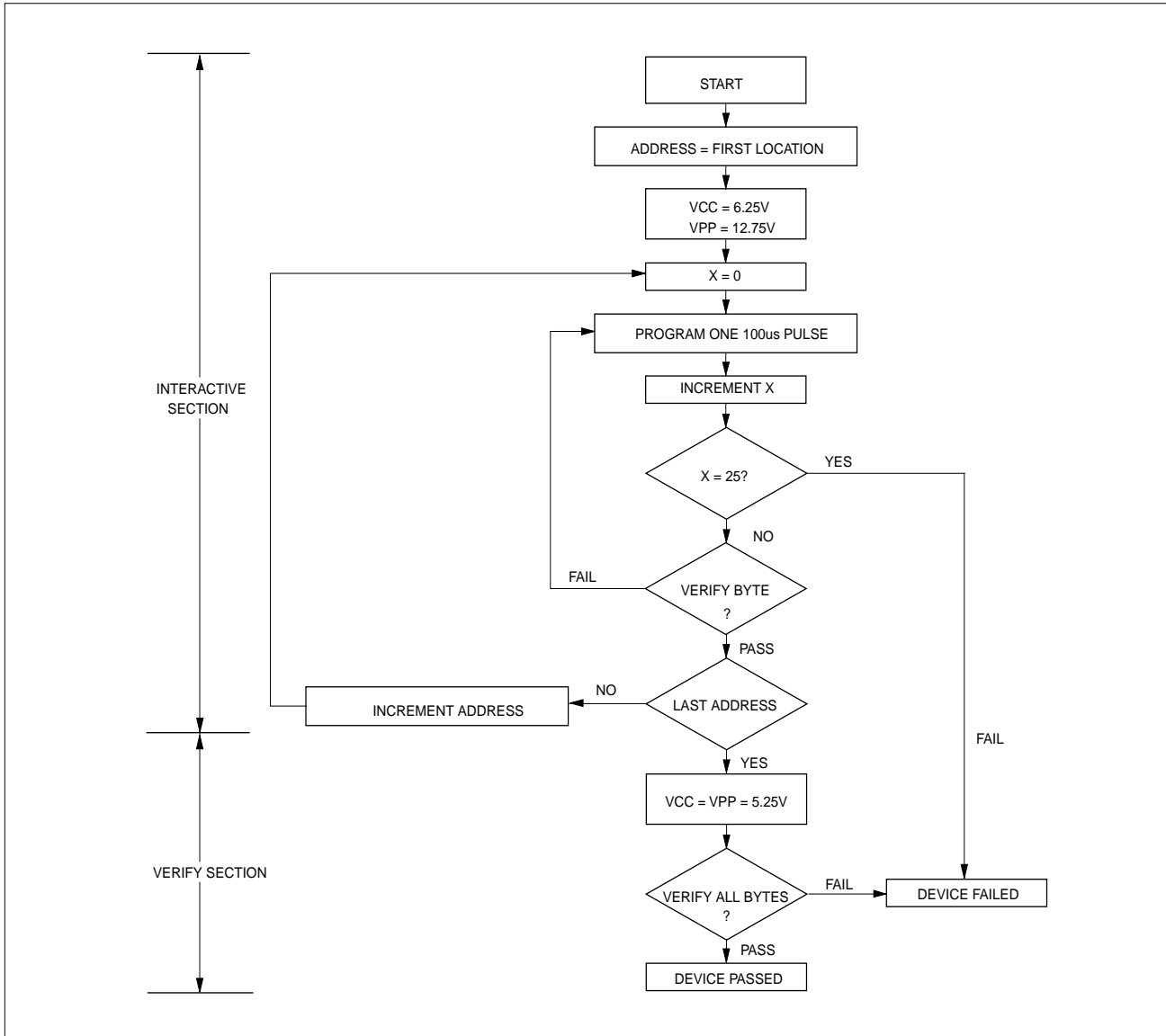
MODE SELECT TABLE

MODE	PINS						
	\overline{CE}	\overline{OE}	\overline{PGM}	A0	A9	VPP	OUTPUTS
Read	VIL	VIL	X	X	X	VCC	DOUT
Output Disable	VIL	V_{IH}	X	X	X	VCC	High Z
Standby (TTL)	V_{IH}	X	X	X	X	VCC	High Z
Standby (CMOS)	$V_{CC} \pm 0.3V$	X	X	X	X	VCC	High Z
Program	VIL	V_{IH}	VIL	X	X	VPP	DIN
Program Verify	VIL	VIL	V_{IH}	X	X	VPP	DOUT
Program Inhibit	V_{IH}	X	X	X	X	VPP	High Z
Manufacturer Code(3)	VIL	VIL	X	VIL	V_{H}	VCC	C2H
Device Code(3)	VIL	VIL	X	V_{IH}	V_{H}	VCC	20H

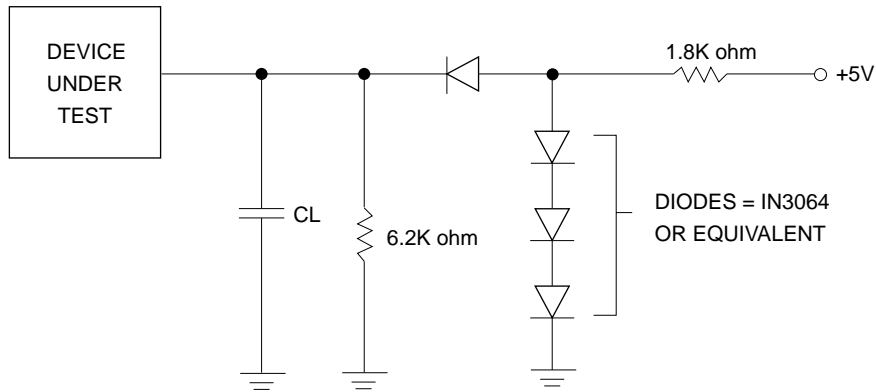
NOTES: 1. $V_{H} = 12.0$ V \pm 0.5 V
 2. X = Either V_{IH} or VIL

3. A1 - A8 = A10 - A17 = VIL(For auto select)
 4. See DC Programming Characteristics for VPP voltage during programming.

FIGURE 1. FAST PROGRAMMING FLOW CHART

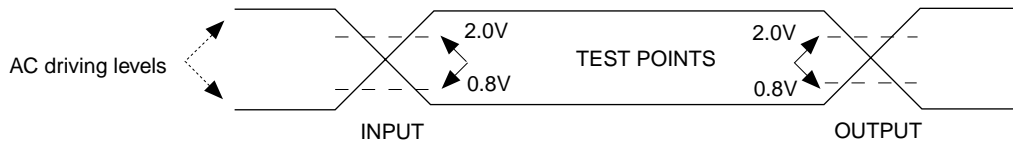


SWITCHING TEST CIRCUITS

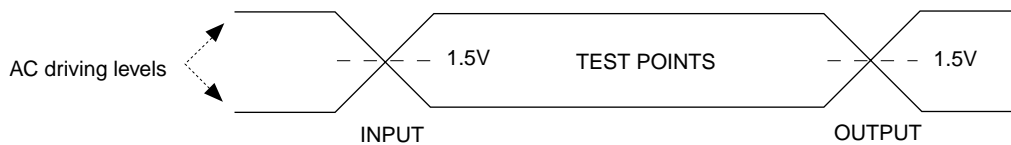


CL = 100 pF including jig capacitance (30pF for MX27L2000-120, 150ns)

SWITCHING TEST WAVEFORMS



AC TESTING: AC driving levels are 3.0V/0V for both commercial grade and industrial grade.
Input pulse rise and fall times are ≤ 10 ns.



AC TESTING: (1) AC driving levels are 3.0V/0V for commercial grade and industrial grade.
Input pulse rise and fall times are ≤ 10 ns.
(2) For MX27L2000-12/15.

ABSOLUTE MAXIMUM RATINGS

RATING	VALUE
Ambient Operating Temperature	-40°C to 85°C
Storage Temperature	-65°C to 125°C
Applied Input Voltage	-0.5V to 7.0V
Applied Output Voltage	-0.5V to VCC + 0.5V
VCC to Ground Potential	-0.5V to 7.0V
V9 & VPP	-0.5V to 13.5V

NOTICE:

Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended period may affect reliability.

NOTICE:

Specifications contained within the following tables are subject to change.

DC/AC Operating Conditions for Read Operation

		MX27L2000			
		-12	-15	-20	-25
Operating Temperature	Commercial	0°C to 70°C	0°C to 70°C	0°C to 70°C	0°C to 70°C
	Industrial	-	-	-40°C to 85°C	-40°C to 85°C
Vcc Power Supply		2.7V to 3.6V	2.7V to 3.6V	2.7V to 3.6V	2.7V to 3.6V

DC CHARACTERISTICS

SYMBOL	PARAMETER	MIN.	MAX.	UNIT	CONDITIONS
VOH	Output High Voltage	2.4		V	IOH = -0.4mA, VCC=3.0V
VOL	Output Low Voltage		0.4	V	IOL = 2.1mA, VCC=3.0V
VIH	Input High Voltage	2.0	VCC + 0.5	V	
VIL	Input Low Voltage	-0.3	0.8	V	2.7V < VCC < 3.6V
ILI	Input Leakage Current	-10	10	uA	VIN = 0 to 3.6V
ILO	Output Leakage Current	-10	10	uA	VOUT = 0 to 5.5V
ICC3	VCC Power-Down Current		20	uA	$\overline{CE} = VCC \pm 0.3V$
ICC2	VCC Standby Current		0.25	mA	$\overline{CE} = VIH$
ICC1	VCC Active Current		20	mA	$\overline{CE} = VIL, f=5MHz, Iout = 0mA, VCC=3.6V$
IPP	VPP Supply Current Read		10	uA	$\overline{CE} = \overline{OE} = VIL, VPP = VCC$

CAPACITANCE TA = 25°C, f = 1.0 MHz (Sampled only)

SYMBOL	PARAMETER	TYP.	MAX.	UNIT	CONDITIONS
CIN	Input Capacitance	8	12	pF	VIN = 0V
COUT	Output Capacitance	8	12	pF	VOUT = 0V
CVPP	VPP Capacitance	18	25	pF	VPP = 0V



AC CHARACTERISTICS

SYMBOL	PARAMETER	27L2000-12		27L2000-15		27L2000-20		27L2000-25		UNIT	CONDITIONS
		MIN	MAX.	MIN.	MAX.	MIN.	MAX.	MIN.	MAX.		
tACC	Address to Output Delay		120		150		200		250	ns	$\overline{CE} = \overline{OE} = VIL$
tCE	Chip Enable to Output Delay		120		150		200		250	ns	$\overline{OE} = VIL$
tOE	Output Enable to Output Delay		50		65		100		120	ns	$\overline{CE} = VIL$
tDF	\overline{OE} High to Output Float, or \overline{CE} High to Output Floa	0	35	0	50	0	60	0	70	ns	
tOH	Output Hold from Address, \overline{CE} or \overline{OE} which ever occurred first	0		0		0		0		ns	

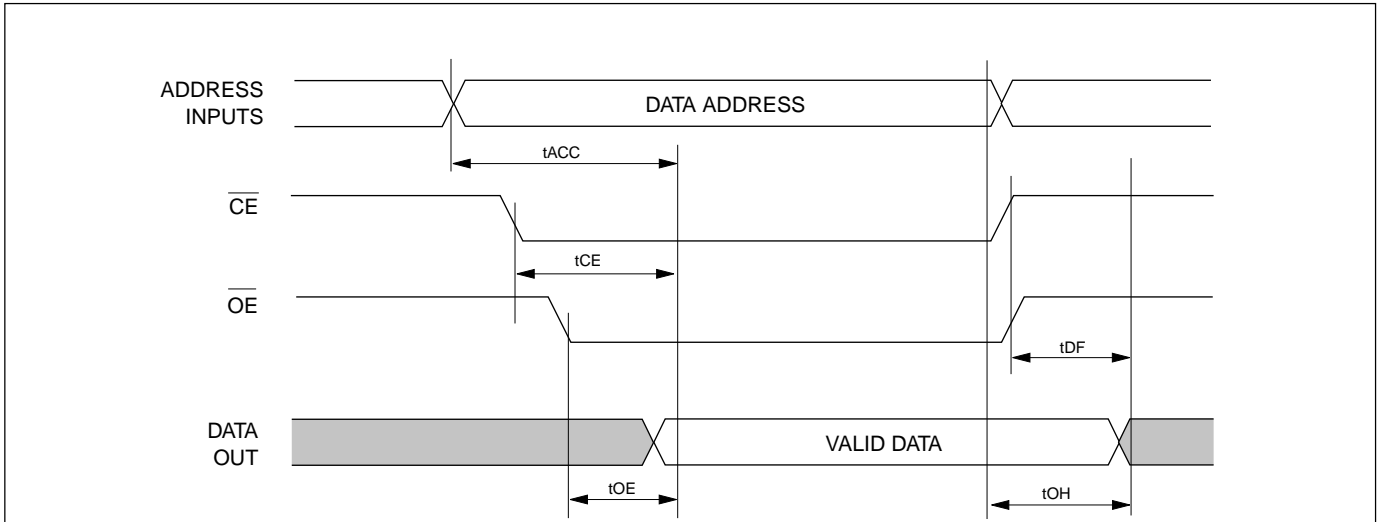
DC PROGRAMMING CHARACTERISTICS TA = 25°C ± 5°C

SYMBOL	PARAMETER	MIN.	MAX.	UNIT	CONDITIONS
VOH	Output High Voltage	2.4		V	IOH = -0.40mA
VOL	Output Low Voltage		0.4	V	IOL = 2.1mA
VIH	Input High Voltage	2.0	VCC + 0.5	V	
VIL	Input Low Voltage	-0.3	0.8	V	
ILI	Input Leakage Current	-10	10	uA	VIN = 0 to 3.6V
VH	A9 Auto Select Voltage	11.5	12.5	V	
ICC3	VCC Supply Current (Program & Verify)		50	mA	
IPP2	VPP Supply Current(Program)		30	mA	$\overline{CE} = \overline{PGM} = VIL, \overline{OE} = VIH$
VCC1	Fast Programming Supply Voltage	6.00	6.50	V	
VPP1	Fast Programming Voltage	12.5	13.0	V	

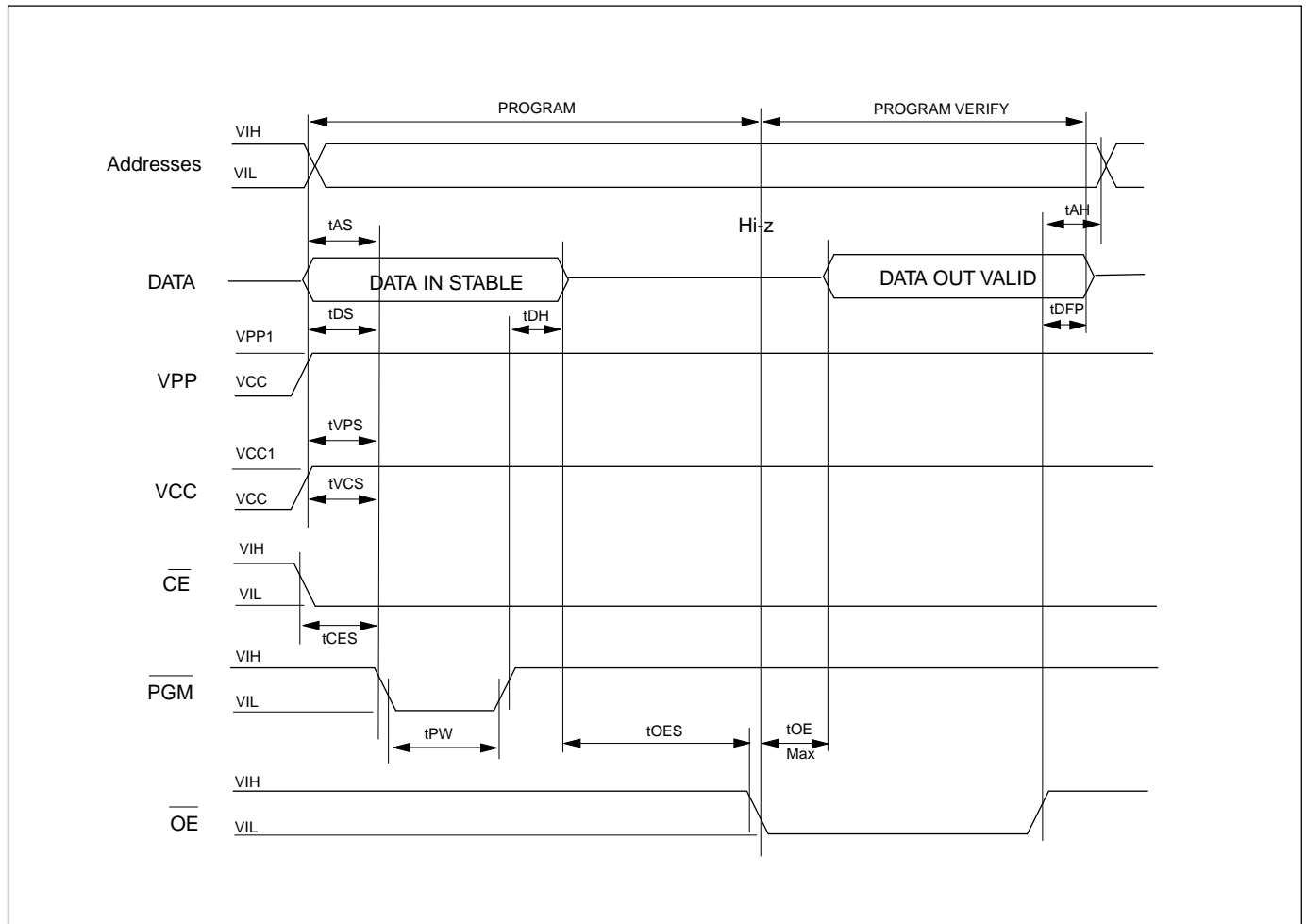
AC PROGRAMMING CHARACTERISTICS TA = 25°C ± 5°C

SYMBOL	PARAMETER	MIN.	MAX.	UNIT	CONDITIONS
tAS	Address Setup Time	2.0		us	
tOES	\overline{OE} Setup Time	2.0		us	
tDS	Data Setup Time	2.0		us	
tAH	Address Hold Time	0		us	
tDH	Data Hold Time	2.0		us	
tDFP	Output Enable to Output Float Delay	0	130	ns	
tVPS	VPP Setup Time	2.0		us	
tPW	\overline{PGM} Program Pulse Width	95	105	us	
tVCS	VCC Setup Time	2.0		us	
tCES	\overline{CE} Setup Time	2		us	
tOE	Data valid from \overline{OE}		150	ns	

WAVEFORMS READ CYCLE



FAST PROGRAMMING ALGORITHM WAVEFORM





ORDERING INFORMATION CERAMIC PACKAGE

PART NO.	ACCESS TIME(ns)	OPERATING	STANDBY	OPERATING	PACKAGE
		CURRENT MAX.(mA)	CURRENT MAX.(uA)	TEMPERATURE	
MX27L2000DC-12	120	20	20	0°C to 70°C	32 Pin DIP
MX27L2000DC-15	150	20	20	0°C to 70°C	32 Pin DIP
MX27L2000DC-20	200	20	20	0°C to 70°C	32 Pin DIP
MX27L2000DC-25	250	20	20	0°C to 70°C	32 Pin DIP
MX27L2000DI-12	120	20	20	-40°C to 85°C	32 Pin DIP
MX27L2000DI-15	150	20	20	-40°C to 85°C	32 Pin DIP
MX27L2000DI-20	200	20	20	-40°C to 85°C	32 Pin DIP
MX27L2000DI-25	250	20	20	-40°C to 85°C	32 Pin DIP

PLASTIC PACKAGE

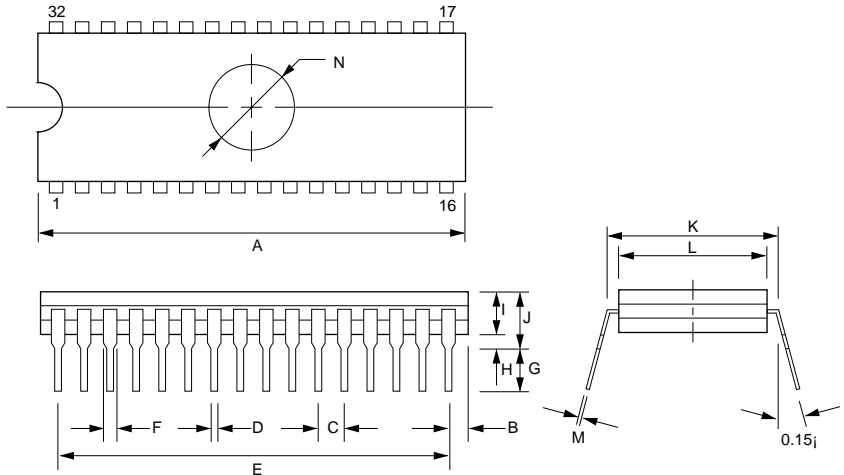
PART NO.	ACCESS TIME(ns)	OPERATING	STANDBY	OPERATING	PACKAGE
		CURRENT MAX.(mA)	CURRENT MAX.(uA)	TEMPERATURE	
MX27L2000PC-12	120	20	20	0°C to 70°C	32 Pin DIP
MX27L2000MC-12	120	20	20	0°C to 70°C	32 Pin SOP
MX27L2000TC-12	120	20	20	0°C to 70°C	8x20mm 32 Pin TSOP(I)
MX27L2000PC-15	150	20	20	0°C to 70°C	32 Pin DIP
MX27L2000MC-15	150	20	20	0°C to 70°C	32 Pin SOP
MX27L2000TC-15	150	20	20	0°C to 70°C	8x20mm 32 Pin TSOP(I)
MX27L2000PC-20	200	20	20	0°C to 70°C	32 Pin DIP
MX27L2000MC-20	200	20	20	0°C to 70°C	32 Pin SOP
MX27L2000TC-20	200	20	20	0°C to 70°C	8x20mm 32 Pin TSOP(I)
MX27L2000PC-25	250	20	20	0°C to 70°C	32 Pin DIP
MX27L2000MC-25	250	20	20	0°C to 70°C	32 Pin SOP
MX27L2000TC-25	250	20	20	0°C to 70°C	8x20mm 32 Pin TSOP(I)
MX27L2000PI-12	120	20	20	-40°C to 85°C	32 Pin DIP
MX27L2000MI-12	120	20	20	-40°C to 85°C	32 Pin SOP
MX27L2000TI-12	120	20	20	-40°C to 85°C	8x20mm 32 Pin TSOP(I)
MX27L2000PI-15	150	20	20	-40°C to 85°C	32 Pin DIP
MX27L2000MI-15	150	20	20	-40°C to 85°C	32 Pin SOP
MX27L2000TI-15	150	20	20	-40°C to 85°C	8x20mm 32 Pin TSOP(I)
MX27L2000PI-20	200	20	20	-40°C to 85°C	32 Pin DIP
MX27L2000MI-20	200	20	20	-40°C to 85°C	32 Pin SOP
MX27L2000TI-20	200	20	20	-40°C to 85°C	8x20mm 32 Pin TSOP(I)
MX27L2000PI-25	250	20	20	-40°C to 85°C	32 Pin DIP
MX27L2000MI-25	250	20	20	-40°C to 85°C	32 Pin SOP
MX27L2000TI-25	250	20	20	-40°C to 85°C	8x20mm 32 Pin TSOP(I)

PLASTIC PACKAGE

PART NO.	ACCESS TIME(ns)	OPERATING	STANDBY	OPERATING	PACKAGE
		CURRENT MAX.(mA)	CURRENT MAX.(uA)	TEMPERATURE	
MX27L2000T2C-12	120	20	20	0°C to 70°C	8x14mm 32 Pin TSOP(I)
MX27L2000T2C-15	150	20	20	0°C to 70°C	8x14mm 32 Pin TSOP(I)
MX27L2000T2C-20	200	20	20	0°C to 70°C	8x14mm 32 Pin TSOP(I)
MX27L2000T2C-25	250	20	20	0°C to 70°C	8x14mm 32 Pin TSOP(I)
MX27L2000T2I-12	120	20	20	-40°C to 85°C	8x14mm 32 Pin TSOP(I)
MX27L2000T2I-15	150	20	20	-40°C to 85°C	8x14mm 32 Pin TSOP(I)
MX27L2000T2I-20	200	20	20	-40°C to 85°C	8x14mm 32 Pin TSOP(I)
MX27L2000T2I-25	250	20	20	-40°C to 85°C	8x14mm 32 Pin TSOP(I)
MX27L2000T3C-12	120	20	20	0°C to 70°C	8x13.4mm 32 Pin TSOP(I)
MX27L2000T3C-15	150	20	20	0°C to 70°C	8x13.4mm 32 Pin TSOP(I)
MX27L2000T3C-20	200	20	20	0°C to 70°C	8x13.4mm 32 Pin TSOP(I)
MX27L2000T3C-25	250	20	20	0°C to 70°C	8x13.4mm 32 Pin TSOP(I)
MX27L2000T3I-12	120	20	20	-40°C to 85°C	8x13.4mm 32 Pin TSOP(I)
MX27L2000T3I-15	150	20	20	-40°C to 85°C	8x13.4mm 32 Pin TSOP(I)
MX27L2000T3I-20	200	20	20	-40°C to 85°C	8x13.4mm 32 Pin TSOP(I)
MX27L2000T3I-25	250	20	20	-40°C to 85°C	8x13.4mm 32 Pin TSOP(I)

PACKAGE INFORMATION
32-PIN CERDIP(MSI) WITH WINDOW (600mil)

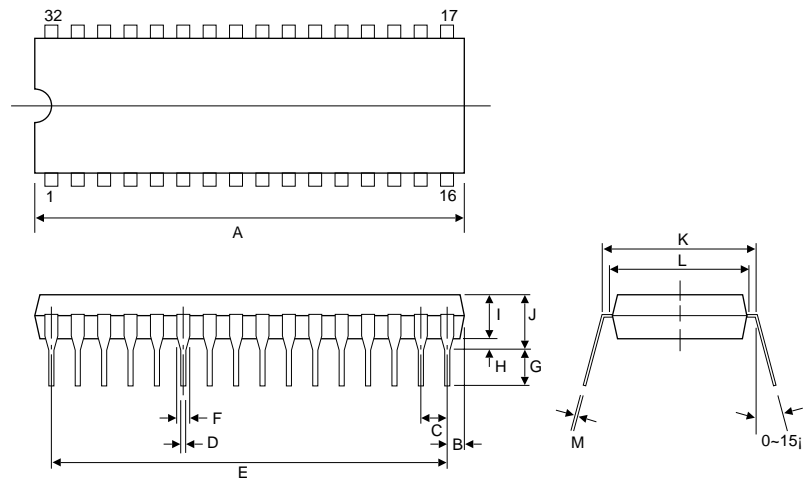
ITEM	MILLIMETERS	INCHES
A	42.26 max	1.665 max
B	1.90 ± .38	.075 ± .015
C	2.54 [TP]	.100 [TP]
D	.46 [REF]	.018 [REF]
E	38.07	1.500
F	1.42 [REF]	.056 [REF]
G	3.43 ± .38	.135 ± .015
H	.96 ± .43	.038 ± .017
I	4.06	.160
J	5.00	.203
K	15.58 ± .13	.614 ± .005
L	13.20 ± .38	.520 ± .015
M	.25 [REF]	.010 [REF]
N	ø8.12	ø.320



NOTE: Each lead centerline is located within .25 mm[.01 inch] of its true position [TP] at maximum material condition.

32-PIN PLASTIC DIP(600 mil)

ITEM	MILLIMETERS	INCHES
A	42.13 max.	1.660 max.
B	1.90 [REF]	.075 [REF]
C	2.54 [TP]	.100 [TP]
D	.46 [Typ.]	.018 [Typ.]
E	38.07	1.500
F	1.27 [Typ.]	.050 [Typ.]
G	3.30 ± .25	.130 ± .010
H	.51 [REF]	.020 [REF]
I	3.94 ± .25	.155 ± .010
J	5.33 max.	.210 max.
K	15.22 ± .25	.600 ± .010
L	13.97 ± .25	.550 ± .010
M	.25 [Typ.]	.010 [Typ.]



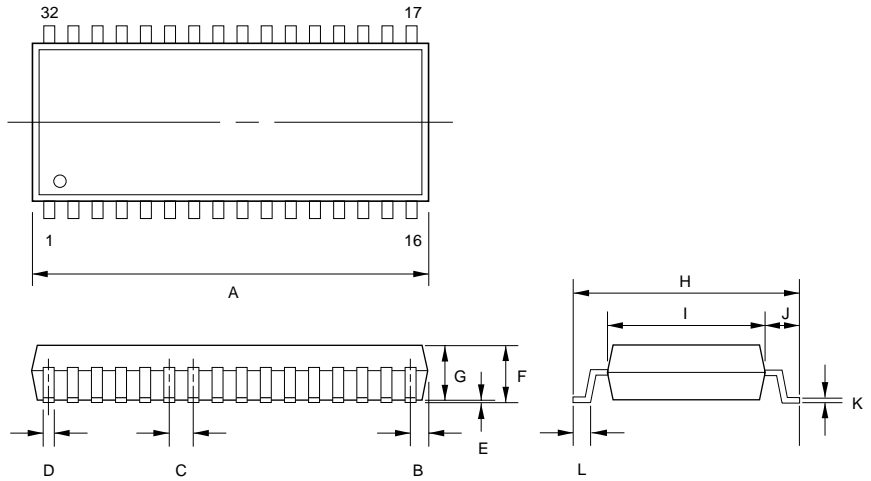
NOTE: Each lead centerline is located within .25 mm[.01 inch] of its true position [TP] at maximum material condition.

PACKAGE INFORMATION(Continued)

32-PIN PLASTIC SOP (450 mil)

ITEM	MILLIMETERS	INCHES
A	20.95 max.	.825 max.
B	1.00 [REF]	.039 [REF]
C	1.27 [TP]	.050 [TP]
D	.40 [Typ.]	.016 [Typ.]
E	.05 min.	.002 min.
F	3.05 max.	.120 max.
G	2.69 ± .13	.106 ± .005
H	14.12 ± .25	.556 ± .010
I	11.30 ± .13	.445 ± .005
J	1.42	.056
K	.20 [Typ.]	.008 [Typ.]
L	.79	.031

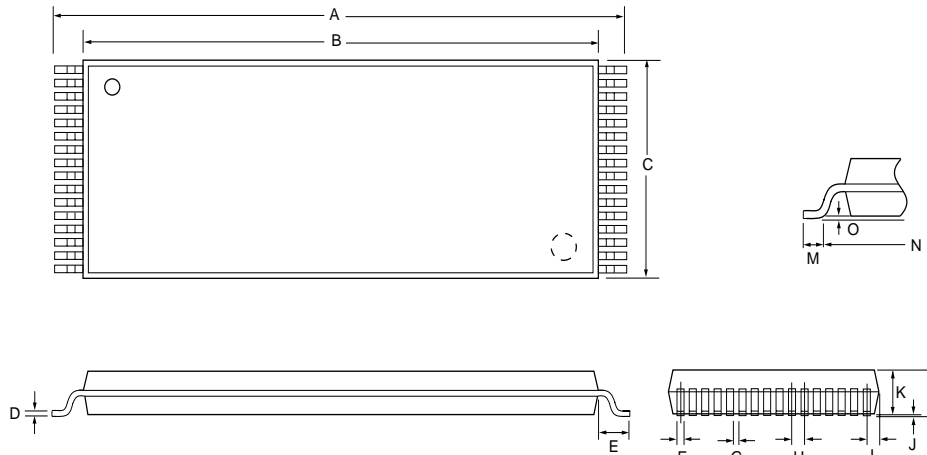
NOTE: Each lead centerline is located within .25 mm [.01 inch] of its true position [TP] at maximum material condition.



32-PIN PLASTIC TSOP

ITEM	MILLIMETERS	INCHES
A	20.0 ± .20	.788 ± .006
B	18.40 ± .10	.724 ± .004
C	8.20 max.	.323 max.
D	0.15 [Typ.]	.006 [Typ.]
E	.80 [Typ.]	.031 [Typ.]
F	.20 ± .10	.008 ± .004
G	.30 ± .10	.012 ± .004
H	.50 [Typ.]	.020 [Typ.]
I	.45 max.	.018 max.
J	0 ~ .20	0 ~ .008
K	1.00 ± .10	.039 ± .004
L	1.27 max.	.050 max.
M	.50	.020
N	0 ~ 5°	.500

NOTE: Each lead centerline is located within .25 mm [.01 inch] of its true position [TP] at maximum material condition.



Revision History

Revision No.	Description	Date
2.0	Eliminate Interactive Programming Mode. AC driving levels changed from 2.4V/0.4V to 3V/0V.	5/29/1997
2.1	IPP 100uA --> 10uA	8/07/1997
2.2	Add 120/150ns speed grades.	12/24/1997
2.3	Corrected errors in the DC/AC Operating Conditions for Read Operation	2/5/1998
2.4	Add 8x14mm and 8x13.4mm 32-TSOP(I) Packages	2/24/1998
2.5	Change TSOP Orientation	4/09/1998

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